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SPECIFICATION

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10C470FB8NNNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 47pF, 50V, ±1%, C0G, 0603

A. Samsung Part Number

<u>CL</u> <u>10</u> <u>C</u> <u>470</u> <u>F</u> <u>B</u> <u>8</u> <u>N</u> <u>N</u> <u>N</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ 8 ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor		
2	Size	0603 (inch code)	L: 1.6 ± 0.1 mm W: 0.8 ± 0.1 mm	
(3)	Dielectric	COG	Inner electrode Ni	
_				
4	Capacitance	47 pF	Termination Cu	
(5)	Capacitance	±1 %	Plating Sn 100% (Pb Free)	
	tolerance		Product Normal	
6	Rated Voltage	50 V	Special Reserved for future use	
7	Thickness	0.8 ± 0.1 mm	Packaging Cardboard Type, 7" reel	

B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition		
Capacitance	Within specified tolerance	1Mb±10% 0.5~5Vrms		
Q	1000 min			
Insulation	10,000Mohm or 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.		
Resistance	Whichever is Smaller			
Appearance	No abnormal exterior appearance	Microscope (×10)		
Withstanding	No dielectric breakdown or	300% of the rated voltage		
Voltage	mechanical breakdown			
Temperature	COG			
Characterisitcs	(From -55 $^{\circ}$ C to 125 $^{\circ}$ C, Capacitance change shoud be within ±30PPM/ $^{\circ}$ C)			
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.		
of Termination	terminal electrode			
Bending Strength	Capacitance change :	Bending to the limit (1mm)		
	within ±5% or ±0.5pF whichever is larger	with 1.0mm/sec.		
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder		
	is to be soldered newly	245±5℃, 3±0.3sec.		
		(preheating : 80~120℃ for 10~30sec.)		
Resistance to	Capacitance change :	Solder pot : 270±5℃, 10±1sec.		
Soldering heat	within ±2.5% or ±0.25pF whichever is larger			
	Tan δ, IR : initial spec.			

	Performance	Test condition
Vibration Test	Capacitance change :	Amplitude : 1.5mm
	within ±2.5% or ±0.25pF whichever is larger	From 10Hz to 55Hz (return : 1min.)
Tan δ, IR : initial spec.		2hours × 3 direction (x, y, z)
Moisture Capacitance change :		With rated voltage
Resistance	within ±7.5% or ±0.75pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs
	Q: 200 min	
IR : 500Mohm or 25Mohm $\cdot \mu$ F		
	Whichever is Smaller	
High Temperature	Capacitance change :	With 200% of the rated voltage
Resistance	within ±3% or ±0.3pF whichever is larger	Max. operating temperature
	Q: 350 min	1000+48/-0hrs
	IR : 1000Mohm or 50Mohm $\cdot \mu$ F	
	Whichever is Smaller	
Temperature	Capacitance change :	1 cycle condition
Cycling	within ±2.5% or ±0.25pF whichever is larger	Min. operating temperatur → 25 ℃
	Tan δ, IR : initial spec.	→ Max. operating temperature → 25°C
		5 cycle test

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}$ C, 10sec. Max)

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.